

Laminated board for printed circuit, having high tracking resistance -
has surface layer of woven glass fibre prepd by impregnating polyepoxy
resin compsn and nonwoven glass fibre core layer.

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Patent Family:

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JP 6302926	A	19941028	JP 9385995	A	19930413	199503 B
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Patent Details:

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Abstract (Basic): JP 6302926 A

Laminated board has surface layer(s) of woven glass fibre prepd by
impregnating an epoxy resin compsn comprising 100 pts wt epoxy resin
free from Br, 10-200 pts wt inorganic filler and nonwoven glass fibre
core layer(s) prepd by impregnating a resin compsn comprising 100 pts
wt brominated epoxy resin and 10-200 pts wt inorganic filler.

The inorganic filler is pref hydrated Al₂O₃ which is decomposed by
discharge heat to form volatile prods and to prevent the tracking. The
epoxy varnish for the surface layer comprises eg 100 pts wt epoxy resin
free from Br, 4 pts wt dicyandiamide, 2 pts wt
2-phenyl-4-methylimidazole, 20 pts wt methylcellosolve, 30 pts wt
acetone and 50 pts wt Al hydroxide of gypside type. The epoxy varnish
for the core layer comprises 100 pts wt brominated epoxy resin, 4 pts
wt dicyandiamide, 0.15 pts wt 2-ethyl-4-methylimidazole, 36 pts wt
methylcellosolve, 60 pts wt acetone and 60 pts wt Al hydroxide of
gypside type.

ADVANTAGE - The laminated board has high tracking resistance,
flame-resistance and peeling strength of Cu foil.

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Title Terms: LAMINATE; BOARD; PRINT; CIRCUIT; HIGH; TRACK; RESISTANCE;
SURFACE; LAYER; WOVEN; GLASS; FIBRE; PREPARATION; IMPREGNATE; POLYEPOXIDE
; RESIN; COMPOSITION; NONWOVEN; GLASS; FIBRE; CORE; LAYER

Derwent Class: A21; A85; L03; P73; V04

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